Proceedings

International Symposium on Physical Design, 2000

San Diego, CA
April 9-12, 2000
Foreword

On behalf of the organizing committee we welcome you to the 2000 International Symposium on Physical Design (ISPD). This time the Symposium is being held in San Diego, California, in the Hyatt Islandia Hotel.

The International Symposium on Physical Design provides a forum for the exchange of ideas and results in the area of physical design of VLSI systems. This meeting evolved from the ACM/SIGDA Physical Design Workshops held during the years 1987-1996. Although interest in physical design dropped off in the early nineties, it has grown back dramatically in recent years. The number of researchers working in this area, and the set of new commercial interests in both start-ups and big companies shows that in the deep sub micron age physical design is economically critical, and intellectually challenging.

This year’s Symposium focuses on CAD algorithms and practices for generating and analyzing deep-sub-micron designs. An outstanding set of technical papers has been selected for oral and poster presentation. All of these papers, whether oral or poster, appear here in the paper and electronic versions of the proceedings. In addition, we will provide access to the foils presented at the conference for those authors who choose to allow that. Please check them out at our new, permanent web site, www.acm.org/ispd.

These papers are complemented by invited speakers, which are marked in the proceedings. Our keynote speaker, Aart de Geus of Synopsys, will give us a hint at the future of physical EDA from the perspective one of the largest companies in EDA. Our banquet speaker, Gadi Singer, will present a talk on large team management issues from a designer perspective. We have three panel sessions on controversial topics. The Bottom-10 Problems panel lets leaders in EDA express views that are not often made public regarding the true value of further research in some topics. EDA and Internet will explore new developments and business approaches to applying the leverage of the web to EDA problems. And the last panel, on floorplanning, addresses an area that has been researched a lot, but which brings strong feelings and disagreement on its value and future directions.

The symposium is sponsored by the ACM Special Interest Group on Design Automation. Generous support has also been provided by (in alphabetical order): Avant! Corporation, IBM Austin Research Laboratory, Intel Corporation, InTime, Magma Design Automation, Monterey Design Systems, and Synopsys.

On behalf of the Technical Program Committees, we sincerely hope that you will find ISPD-2000 useful, and informative, and fun!

Manfred Wiesel
Technical Program Chair

Dwight Hill
General Chair
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Acknowledgements

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